

Certificate TW16/00475

The management system of

Unimicron Technology Corporation Hsinfeng I Plant

No. 289 & 290, Zhonglun Village, Xinfeng Township, Hsinchu County 304, Taiwan (R.O.C.)

has been assessed and certified as meeting the requirements of
ISO 45001:2018

For the following activities

Unimicron Technology Corporation Hsinfeng I Plant

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(HF)

Unimicron Technology Corporation Dayuan Plant

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (LC3)

Unimicron Technology Corporation Yangmei Plant

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(YM)

This certificate is valid from 25 June 2022 until 25 June 2025 and remains valid subject to satisfactory surveillance audits.

Issue 4. Certified since 25 June 2019.

Certified activities performed by additional sites are listed on subsequent pages.

Authorised by



SGS Taiwan Ltd.

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Management System
Certification
MS001



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Certificate TW16/00475, continued

Unimicron Technology Corporation Hsinfeng I Plant

ISO 45001:2018

Issue 4
Sites
Unimicron Technology Corporation Hsinfeng I Plant No. 289 & 290, Zhonglun Village, Xinfeng Township, Hsinchu County 304, Taiwan (R.O.C.) The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(HF)
Unimicron Technology Corporation Dayuan Plant No.5, Minquan Rd., Dayuan Dist., Taoyuan City 337, Taiwan (R.O.C.) The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (LC3)
Unimicron Technology Corporation Yangmei Plant No.66.68.70, Ln 426, Sec.1, Meishi Rd. Yangmei Dist., Taoyuan City 326, Taiwan (R.O.C.) The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(YM)



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